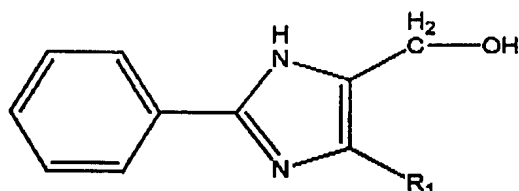


What is claimed is:

1. A paste for filling a throughhole, which comprises:  
an epoxy resin; a curing agent; and a metal filler, wherein  
the metal filler is a powder comprising a base metal, and the  
5 curing agent is an imidazole compound represented by the  
following formula (1):



(1)

- wherein R<sub>1</sub> represents a hydrogen atom, an alkyl group having  
10 1 to 10 carbon atoms, a hydroxyalkyl group having 1 to 10 carbon  
atoms or an alkyloxy group having 1 to 10 carbon atoms.

2. The paste for filling a throughhole according to claim  
1, which further comprises an inorganic filler.

15

3. The paste for filling a throughhole according to claim  
1 or 2, which further comprises an ultrafine inorganic filler.

4. The paste for filling a throughhole according to claim  
20 3, wherein the ultrafine inorganic filler has a specific surface  
area by BET method of 40 to 400 m<sup>2</sup>/g.

5. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler has a specific surface area by BET method of 60 to 100 m<sup>2</sup>/g.

5 6. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler has a primary particle size of 5 to 50 nm.

10 7. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler has a primary particle size of 10 to 20 nm.

15 8. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler has an apparent specific gravity of 30 to 200 g/l.

20 9. The paste for filling a throughhole according to claim 3, wherein a 4% dispersion of the ultrafine inorganic filler in 1:1 solution of water and methanol shows a pH value of 4.5 to 6.5.

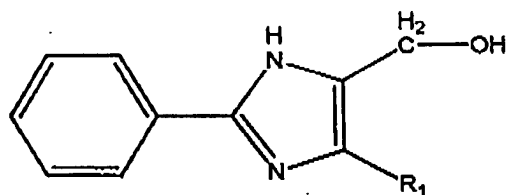
25 10. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler contains an organic ingredient in an amount of 3 to 5% by weight in terms of carbon.

11. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler has a water content of 0.05 to 0.15% by mass.

5 12. The paste for filling a throughhole according to claim 3, wherein the ultrafine inorganic filler comprises at least one inorganic ingredient including a major inorganic ingredient, and the ratio of the major inorganic ingredient is 99.5 mass% or more based on the total of the at least one inorganic  
10 ingredient.

13. A printed wiring board comprising: a substrate having a conductor layer; and a throughhole penetrating through the substrate,

15 wherein the throughhole is filled with a paste to be subjected to curing; the paste comprises an epoxy resin, a curing agent and a metal filler; the metal filler is a powder comprises a base metal; and the curing agent is an imidazolic compound represented by the following formula (1):



(1)

20 wherein R<sub>1</sub> represents a hydrogen atom, an alkyl group containing

1 to 10 carbon atoms, a hydroxyalkyl group containing 1 to 10 carbon atoms or an alkyloxy group containing 1 to 10 carbon atoms.

5        14. The printed wiring board according to claim 13, wherein the paste further comprises an inorganic filler.

10        15. The printed wiring board according to claim 13, wherein the paste further comprises an ultrafine inorganic filler.

15        16. The printed wiring board according to claim 13, wherein at least part of the surface of the conductor layer has been subjected to a treatment of imparting hydrophobicity so that the treated surface part has a contact angle against water of 90 degrees or higher.

20        17. The printed wiring board according to claim 13, wherein at least part of the conductor layer has been subjected to a roughing treatment so that the treated surface part has a roughness: Rz of 0.3 to 20  $\mu\text{m}$ .

25        18. The printed wiring board according to claim 13, wherein the substrate comprises a core substrate having on at least one side thereof a build-up layer formed by alternately

laminating an insulating layer and a conductor layer, and the throughhole penetrates through both the core substrate and the build-up layer.

5           19. A multi-layer printed wiring board, which comprises a printed wiring board according to claim 13, and a build-up layer formed by alternately laminating an insulating layer and a conductor layer.

10           20. The multi-layer printed wiring board according to claim 19, wherein the multi-layer wiring board is a PGA type wiring board.